FUTEK
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EMC Compliance Statement and Test Summary

FUTEK, Inc. confirms that the products and product families identified below have been evaluated for electromagnetic compatibility under the applicable requirements and conditions summarized in this document.

Product Description	Covered Model or Product Family
Ultra-Miniature mV/V to SPI/UART Digital Interface Module	IEM100 / QIA128
Compact mV/V to SPI/UART Digital Signal Conditioner	IDC150
FUTEK products incorporating the IEM100/QIA128 module architecture	Applicable FUTEK sensor models and product families*

Coverage applies only to products for which FUTEK has determined that the electrical implementation, operating conditions, power configuration, exposed interfaces, cabling, enclosure, and EMC protection are technically consistent with the evaluated configurations. The inclusion of additional models is subject to FUTEK's internal conformity assessment.

Region	Applicable Regulatory Requirement
European Union	CE conformity under Directive 2014/30/EU - Electromagnetic Compatibility Directive*
United States	FCC 47 CFR Part 15, Subpart B, Class B
Canada	ICES-003 Issue 7, Class B

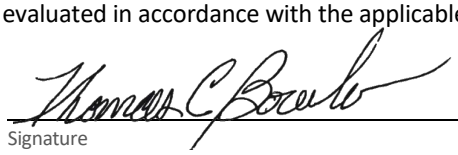
FUTEK, Inc. hereby declares under its sole responsibility that the products identified in this document conform to the applicable requirements of Directive 2014/30/EU, based on the standards and conformity assessment summarized herein.

EMC Standards		
Specifications - Emissions	**Test Method**	**Test Description**
EN IEC 61326-1:2021 Class B	CISPR 11:2015 +A1:2016 +A2:2019	Radiated Emissions Conducted Emissions
FCC 15.107 Class B	ANSI C63.4:2014	
FCC 15.109 Class B		
FCC 15.109(g) Class B		
ICES-003 Issue 7:2020 Class B		
IEC 60601-1-2:2014 + A1:2020 Class B*	CISPR 11:2015 +A1:2016 +A2:2019	
Specifications - Immunity	**Test Method**	**Test Description**
EN IEC 61326-1:2021	IEC 61000-4-2:2008	Electrostatic Discharge (ESD) Radiated Immunity Radiated Immunity - Proximity Fields from RF Wireless Communications Equipment Electrical Fast Transients and Bursts (EFT) Conducted Immunity Magnetic Field Immunity Magnetic Field Immunity - Proximity Fields
	IEC 61000-4-3:2020	
	IEC 61000-4-4:2012	
	IEC 61000-4-6:2013	
	IEC 61000-4-8:2009	
IEC 60601-1-2:2014 + A1:2020*	IEC 61000-4-39:2017	

IEC 60601-1-2 entries represent additional medical EMC evaluations only and do not constitute certification or approval of the covered products as medical electrical equipment or systems.

I, the undersigned, declare on behalf of FUTEK, Inc. that the information contained in this statement is accurate and that the products and product families identified herein have been evaluated in accordance with the applicable EMC requirements and conditions stated in this document.

Irvine, CA USA
Place


Signature

8/01/2026
Date

Thomas C. Bowles
Print Name

Director of Quality Assurance
Title

FUTEK is certified to:

ANSI Z540-1 · ISO 17025 · ISO 9001 · ISO 13485

U.S. Manufacturer

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EMC Evaluation Scope and Integration Information

SCOPE OF EMC EVALUATION

This statement applies to the products and product families identified in this document under the evaluated or technically equivalent configurations. The IEM100/QIA128 was evaluated as an integrable electronic module connected to external host equipment and is not, by itself, a complete standalone end product. Products incorporating the IEM100/QIA128 architecture may be included where FUTEK has determined that the electrical implementation, operating conditions, power configuration, exposed interfaces, cabling, enclosure, grounding, shielding, and EMC protection are consistent with or provide equivalent protection to the evaluated configurations. Final EMC performance remains dependent on the completed product design and application. The manufacturer or system integrator of equipment incorporating these products remains responsible for confirming compliance with all applicable regulatory, functional, and safety requirements. The IDC150 results apply to its evaluated enclosed configuration.

TEST CONFIGURATION AND OBSERVED PERFORMANCE

Testing was performed in normal operating mode at 1300 samples per second using a simulated 1 mV/V transducer input. The evaluated configurations met the applicable Class B radiated and conducted emissions limits. Radiated RF, conducted RF, power-frequency magnetic-field, magnetic-field proximity, RF wireless proximity-field, and input-side EFT/Burst evaluations met the applicable performance criteria.

During ESD testing, the evaluated devices met Performance Criterion C at the higher applied levels, meaning that a power cycle was required to restore normal operation. No permanent damage, flash-memory corruption, loss of stored data, or post-test functional anomalies were observed. The suitability of this recovery behavior, including any temporary measurement variation during electromagnetic disturbances, should be assessed for the final application.

- **IEM100/QIA128 bare-module configuration:** No anomalies were observed at ±2 kV. At the higher applied level (±4 kV), the device became temporarily unresponsive and normal operation was restored following a power cycle.
- **IDC150 enclosed configuration:** No anomalies were observed through ±4 kV. At higher applied levels (±8 kV and ±15 kV), the device became temporarily unresponsive, and normal operation was restored following a power cycle.

EFT/BURST EVALUATION LIMITATION

The sensor-input interfaces were evaluated for EFT/Burst immunity using extended cable lengths. The digital output interfaces were not directly subjected to EFT/Burst because operation and monitoring required connection to host equipment that could not be adequately isolated from the evaluated product. Accordingly, any externally accessible or extended digital communication interface not represented by the evaluated configuration should be assessed as part of the completed product or system.

GENERAL INTEGRATION CONSIDERATIONS

EMC performance may be influenced by power quality, host-board layout, grounding, shielding, enclosure construction, cable type, cable length and routing, interface exposure, and the protection methods used in the completed product. The final design should incorporate appropriate EMC practices, including power-entry filtering and transient suppression, low-impedance grounding, controlled shield termination, separation and routing of sensitive analog and digital signals, suitable interface protection, and appropriate cable selection and termination.

Programming, test, and debug connections should remain inaccessible during normal operation unless they are specifically designed and validated for external use. Externally accessible or extended interfaces should be evaluated in the completed product configuration.

PRECISION MEASUREMENT AND SYSTEM-LEVEL VALIDATION

Protection, filtering, or suppression components added to precision sensor, excitation, or measurement paths should be selected and validated to confirm that leakage current, impedance imbalance, offset, noise, bandwidth, or other effects do not introduce unacceptable measurement error. Applications requiring uninterrupted operation, automatic recovery, maintained communication, or defined measurement accuracy during electromagnetic disturbances should be evaluated and validated at the completed-product or system level under the intended operating conditions.

MEDICAL EMC CONSIDERATIONS

Evaluation to IEC 60601-1-2 addresses electromagnetic compatibility requirements only and does not constitute certification or approval of the covered products as medical electrical equipment. It does not include assessment of basic safety, essential performance, risk management, usability, labeling, software lifecycle requirements, or other medical-device regulatory obligations. Any use of the covered products within medical electrical equipment or systems must be evaluated and validated as part of the completed equipment for its intended use.